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June 25, 2001

ATTORNEY DOCKET NO.: 04329.2583
CUSTOMER NUMBER: 22,852

Box Patent Application
Assistant Commissioner for Patents
Washington, D.C. 20231

New U.S. Patent Application

Title: SEMICONDUCTOR RESIN MOLD AND SEMICONDUCTOR RESIN
MOLDING METHOD USING THE MOLD

Inventor Name and Residence:

1. Mika KIRITANI, Kawasaki-shi, Japan

Sir:

We enclose the following papers for filing in the United States Patent and Trademark Office in connection with the above patent application.

1. Application - 30 pages, including 2 independent claims and 19 claims total.
2. Drawings - 5 sheets of formal drawings containing 12 figures.
3. Information Disclosure Statement and Information Disclosure Citation, PTO 1449 with 3 documents attached.
4. The filing fee is calculated as follows:

Basic Application Filing Fee				\$710	\$ 710.00
	Number of Claims	Basic	Extra Claims		
Total Claims	19	-	20	x \$18	
Independent Claims	2	-	3	x \$80	
[] Presentation of Multiple Dep. Claim(s)				+\$270	
				Subtotal	\$ 710.00
				Reduction by 1/2 if small entity	-
				TOTAL APPLICATION FILING FEE	\$ 710.00

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5. A check for \$710.00 is enclosed for the filing fee.

This application is being filed under the provisions of 37 C.F.R. § 1.53(f). Applicant awaits notification from the Patent and Trademark Office of the time set for filing the Declaration.

Applicant claims the right to priority based on Japanese Application No. 2000-190547, filed June 26, 2000.

Please address all correspondence with respect to this application to:

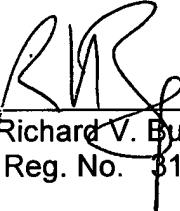
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Please accord this application a serial number and filing date.

The Commissioner is hereby authorized to charge any additional filing fees due and any other fees due under 37 C.F.R. § 1.16 or § 1.17 during the pendency of this application to our Deposit Account No. 06-0916.

Respectfully submitted,
FINNEGAN, HENDERSON, FARABOW,
GARRETT & DUNNER, L.L.P.

By:


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RVB/FPD/peg
Enclosures